02-18-1999

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ET

IBM Docket No.: HQ9-98-091

To the Honorable Commissioner of Pa

d original documents or copy thereof.

1. Name of conveying party(ies):

Farid Agahi **Gary Bronner**
Herbert Ho **Radhika Srinivasan**

MLD
2-5-99

Additional name(s) of conveying party(ies) attached?
[ ] Yes [X] No

3. Nature of Conveyance:

[X] Assignment [ ] Merger
[ ] Security Agreement [ ] Change of Name
[ ] Other

Execution Date: 1/12/99, 1/12/99, 1/14/99, 1/20/99

ddress of receiving party(ies):

Name: **International Business Machines Corporation**
Internal Address: N/A
Street Address: **New Orchard Road**
City: **Armonk** State: **New York**
Zip Code: **10504**

jc518 U.S. PTO
09/245958
02/05/99

Additional Name(s) & Address(es) attached?
[ ] Yes [X] No

4. Application number(s) or patent number(s):

Title of Application: **"SHALLOW TRENCH ISOLATION (STI) WITH BILAYER OF OXIDE-NITRIDE FOR VLSI APPLICATIONS"**

If this document is being filed together with a new application, the execution date of the application is: 1/12; 1/12; 1/14; 1/20, 1999.

02/17/1999 SBURNS 00000038 090458 09245958
01 FC:581 40.00 CH

A. Patent Application No.(s) B. Patent No.(s)

09/245,958

Additional numbers attached? [ ] Yes [ ] No

5. Name and address of party whom correspondence concerning document should be mailed:

Name: **DeLIO & PETERSON, LLC**
Street Address: **121 Whitney Avenue**
City: **New Haven** State: **CT**
Zip Code: **06510-1241**

CERTIFICATE OF MAILING UNDER 37 CFR 1.10

I hereby certify that, on the date shown below, this correspondence is being deposited with the United States Postal Service in an envelope addressed to the Commissioner of Patents and Trademarks, Box Assignments, Washington, D.C. 20231, as "Express Mail Post Office to Addressee" Mailing Label No. EE468937860US

on February 5, 1999
RobinAnn Zeno
Name of person mailing paper
Signature
Date: 2/5/99

6. Total number of applications and patents involved:.......................[1]

7. Total Fee (37 CFR 3.41) $**40.00**
[ ] Enclosed
[X] Authorized to be charged to Deposit Account number below
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8. Assignee IBM Corporation Deposit Account Number:

09-0458

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

H. Daniel Schnurmann
Name of Person Signing
Registration No. **35,791**

Signature
Phone No.: **914-894-2481**

February 5, 1999
Date

Total number of pages including cover sheet, attachments, and document: [5]

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FI-069

IBM Docket No.: HQ9-98-091

ASSIGNMENT

Whereas, we

Inventor and City
(1) **FARID AGAHI**
County of **TRAVIS**
City of **AUSTIN**
and State of **TEXAS**

and

(2) **GARY BRONNER**
County Of **DUTCHESS**
City Of **STORMVILLE**
and State of **NEW YORK**

and

(3) **HERBERT HO**
County of **ORANGE**
City of **NEW WINDSOR**
and State of **NEW YORK**

and

(4) **RADHIKA SRINIVASAN**
County of **BERGEN**
City of **MAHWAH**
and State of **NEW JERSEY**

Title

have invented certain improvements in
"SHALLOW TRENCH ISOLATION (STI) WITH BILAYER OF OXIDE-NITRIDE FOR VLSI APPLICATIONS"

Date That Inventors Signed the Declaration

and have executed, respectively, a United States patent application therefor on
(1) Farid Agahi 1/12, 1999, and (2) ________, 19___,
and (3) ________, 19___, and (4) ________, 19___.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

ASSIGNMENT (continued) IBM DOCKET NO. HQ9-98-091

TITLE: "SHALLOW TRENCH ISOLATION (STI) WITH BILAYER OF OXIDE-NITRIDE FOR VLSI APPLICATIONS"

City (1) Signed at Austin, City Texas State

Date on 1 / 12, 19 99 Farid Agahi signature

FARID AGAHI

City (2) Signed at East Fishkill City New York State

Date on ______, 19__ ______ signature

GARY BRONNER

(3) Signed at East Fishkill City New York State

Date on ______, 19__ ______ signature

HERBERT HO

City (4) Signed at East Fishkill City New York State

Date on ______, 19__ ______ signature

RADHIKA SRINIVASAN

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ASSIGNMENT

Whereas, we

Inventor and City	(1) **FARID AGAHI** County of **TRAVIS**	City of **AUSTIN** and State of **TEXAS**
and		
	(2) **GARY BRONNER** County Of **DUTCHESS**	City Of **STORMVILLE** and State of **NEW YORK**
and		
	(3) **HERBERT HO** County of **ORANGE**	City of **NEW WINDSOR** and State of **NEW YORK**
and		
	(4) **RADHIKA SRINIVASAN** County of **BERGEN**	City of **MAHWAH** and State of **NEW JERSEY**

have invented certain improvements in

Title

"SHALLOW TRENCH ISOLATION (STI) WITH BILAYER OF OXIDE-NITRIDE FOR VLSI APPLICATIONS"

Date That Inventors Signed the Declaration

and have executed, respectively, a United States patent application therefor on
(1) ________________, 19___, and (2) January 12, 1999,
and (3) January 14, 1999, and (4) January 20, 1999.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

TITLE: "SHALLOW TRENCH ISOLATION (STI) WITH BILAYER OF OXIDE-NITRIDE FOR VLSI APPLICATIONS"

City (1) Signed at Austin (City) Texas (State)

Date on ______, 19 99 ______ signature

FARID AGAHI

City (2) Signed at East Fishkill (City) New York (State)

Date on Jan 12, 19 99 ______ signature

GARY BRONNER

(3) Signed at East Fishkill (City) New York (State)

Date on JAN 14, 19 99 ______ signature

HERBERT HO

City (4) Signed at East Fishkill (City) New York (State)

Date on Jan 20, 1999 Radhika Srinivasan signature

RADHIKA SRINIVASAN

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